Appl No.10/600,039 Amdt. dated October 23, 2003

Amendments to the Specification:

The last sentence in the first paragraph under "Detailed Description of the Present Invention", on page 5 should be deleted, and replaced with the following:

"As can be seen therein, the Cu electrofill 15 is separated from the interlevel dielectric ("ILD") 14 by the Cu seed layer 11, the Ta layer 12 and a TaN layer 13."